Statement of Materials, Construction

LEAD-FREE -- 14L-TSSOP -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Ag Plated Cu	0.01786	Cu	7440-50-8	0.01682	30.63434	94.15
				Fe	7439-89-6	0.00004	0.06508	0.20
				Mg	7439-95-4	0.00003	0.05694	0.175
				Ni	7440-02-0	0.00057	1.04121	3.20
				Ag	7440-22-4	0.00004	0.06508	0.20
				Si	7440-21-3	0.00013	0.23590	0.725
				Zn	7440-66-6	0.00018	0.32538	1.00
				Mn	7439-96-5	0.00002	0.03254	0.10
				Silver (plating)	7440-22-4	0.00004	0.06508	0.20
				Pb	7439-92-1	0.00001	0.01627	0.05
2	Die	Silicon Chip	0.00300	Si	7440-21-3	0.00299	5.43815	99.5
3	Die Attach Material	Conductive Epoxy	0.00136	Epoxy Resin	Proprietary	0.00020	0.37165	15.0
				Silver	7440-22-4	0.00108	1.96976	79.5
				Aromatic Amine	Proprietary	0.00007	0.13627	5.5
4	Wire	Gold	0.0003	Au	7440-57-5	0.00030	0.54649	99.99
5	Lead Finish	Tin	0.0011	Sn	7440-31-5	0.00110	2.00401	100
6	Encapsulation	Epoxy Resin	0.03127	Fused Silica	60676-86-0	0.02736	49.84742	87.5
				Epoxy Resin	Proprietary	0.00172	3.13327	5.5
				Phenol Resin	Proprietary	0.00172	3.13327	5.5
				Brominated Epoxy Resin	68541-56-2	0.00017	0.31333	0.55
				Carbon Black	1333-86-4	0.00009	0.17091	0.3
				Antimony Trioxide	1309-64-4	0.00013	0.22787	0.4
Total Package Weight			0.05489					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%